

NOT RECOMMENDED FOR NEW DESIGN USE DMG2307L



DMP3100L

P-CHANNEL ENHANCEMENT MODE MOSFET

Features

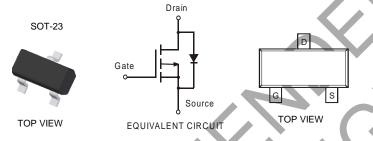
Low On-Resistance:

100mΩ @ V_{GS} = -10V, I_D = -2.7A 170mΩ @ V_{GS} = -4.5V, I_D = -2.0A

- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead Free By Design/RoHS Compliant (Note 2)
- "Green" Device (Note 4)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.008 grams (approximate)



Maximum Ratings @T_A = 25°C unless otherwise specified

Characte	ristic	Symbol	Value	Units
Drain-Source Voltage		V _{DSS}	-30	V
Gate-Source Voltage		V_{GSS}	±20	V
Drain Current (Note 1) V _{GS} = -10V	Steady $T_A = 25$ °C $T_A = 70$ °C	lo	-2.7 -2	А
Pulsed Drain Current (Note 3)		I _{DM}	-8	Α

Thermal Characteristics

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 1)	P_{D}	1.08	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 1)	$R_{ heta JA}$	115	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

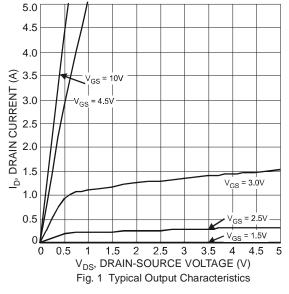
Electrical Characteristics @TA = 25°C unless otherwise specified

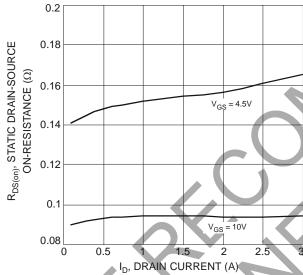
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)							
Drain-Source Breakdown Voltage	BV _{DSS}	-30			V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}			-800	nA	$V_{DS} = -30V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}			±80 ±800	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$ $V_{GS} = \pm 15V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	$V_{GS(th)}$	-1.3	-1.8	-2.1	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$	
Static Drain-Source On-Resistance	R _{DS (ON)}		86 147	100 170	mΩ	$V_{GS} = -10V, I_D = -2.7A$ $V_{GS} = -4.5V, I_D = -2.0A$	
Forward Transfer Admittance	Y _{fs}		3.6		S	$V_{DS} = -5V, I_{D} = -2.7A$	
Diode Forward Voltage (Note 5)	V_{SD}	_	_	-1.26	V	$V_{GS} = 0V, I_{S} = -2.7A$	
DYNAMIC CHARACTERISTICS							
Input Capacitance	Ciss		227		pF	1/ 401/1/ 01/	
Output Capacitance	Coss		64		pF	$V_{DS} = -10V, V_{GS} = 0V$ - f = 1.0MHz	
Reverse Transfer Capacitance	Crss		36		pF	71 = 1.01VII 1Z	

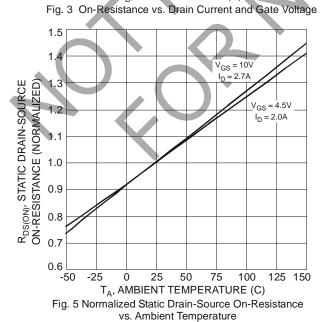
Notes: 1. Device mounted on FR-4 PCB. t ≤5 sec.

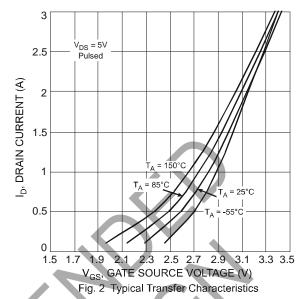
- 2. No purposefully added lead.
- 3. Pulse width $\leq 10 \mu S$, Duty Cycle $\leq 1\%$.
- 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- 5. Short duration pulse test used to minimize self-heating effect.











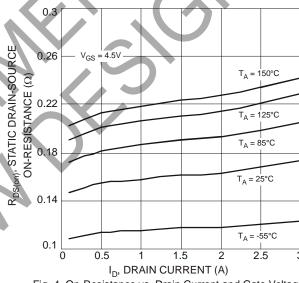
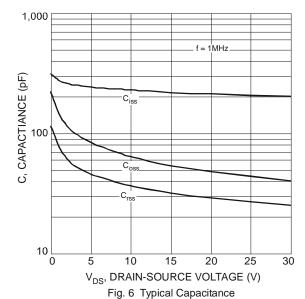


Fig. 4 On-Resistance vs. Drain Current and Gate Voltage





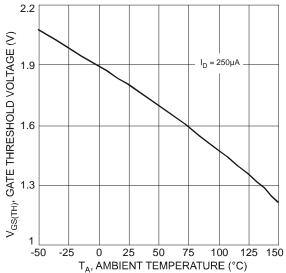


Fig. 7 Gate Threshold Voltage vs. Ambient Temperature

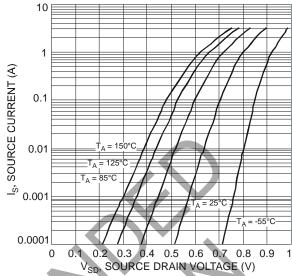


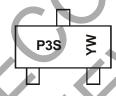
Fig. 8 Reverse Drain Current vs. Source-Drain Voltage

Ordering Information (Note 6)

Part Number	Case	Packaging
DMP3100L-7	SOT-23	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information

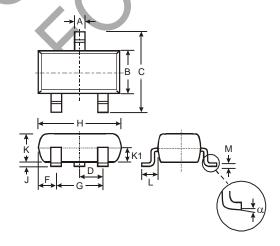


P3S = Product Type Marking Code YM = Date Code Marking Y = Year (ex: U = 2007) M = Month (ex: 9 = September)

Date Code Key

Year	20	07	20	08	20	09	20	10	20	11	20	12
Code		J	1		V	V		(\	1	Z	7
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

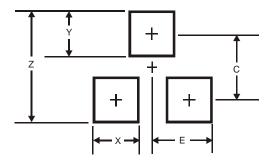
Package Outline Dimensions



SOT-23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
K	0.903	1.10	1.00		
K1	-	-	0.400		
L	0.45	0.61	0.55		
М	0.085	0.18	0.11		
α	0°	8°	-		
All	All Dimensions in mm				



Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35

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